


[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#) |

Welcome United States Patent and Trademark Office

☐ Search Results

BROWSE

SEARCH

IEEE XPLORE GUIDE

Results for "((ansys<in>metadata) <and> (temperature<in>metadata))<and> (semicondu..."

e-mail

Your search matched 13 of 1235066 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

» Search Options

[View Session History](#)[New Search](#)

Modify Search

☐ Check to search only within this results setDisplay Format: ☒ Citation ☐ Citation & Abstract

» Key

IEEE JNL IEEE Journal or Magazine

IEEE JNL IEEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEEE CNF IEEE Conference Proceeding

IEEE STD IEEE Standard

Select Article Information

- ☐ 1. **Temperature and stress distribution in the SOI structure during fabrication**
Cher Ming Tan; Zhenghao Gan; Xiaofang Gao;
Semiconductor Manufacturing, IEEE Transactions on
Volume 16, Issue 2, May 2003 Page(s):314 - 318
Digital Object Identifier 10.1109/TSM.2003.811886
[AbstractPlus](#) | [References](#) | Full Text: [PDF\(354 KB\)](#) IEEE JNL
- ☐ 2. **Thermal transient modeling and experimental validation in the European**
Pape, H.; Schweitzer, D.; Janssen, J.H.J.; Morelli, A.; Villa, C.M.;
Components and Packaging Technologies, IEEE Transactions on [see also Cc
Packaging and Manufacturing Technology, Part A: Packaging Technologies, IE
on]
Volume 27, Issue 3, Sept. 2004 Page(s):530 - 538
Digital Object Identifier 10.1109/TCAPT.2004.831791
[AbstractPlus](#) | [References](#) | Full Text: [PDF\(1040 KB\)](#) IEEE JNL
- ☐ 3. **Crystal SiGeC far infrared sensor with temperature isolation improvemen**
Ming-Chun Hsieh; Yean-Kuen Fang; Pei-Ming Wu; Wen-De Wang;
Electronics Letters
Volume 39, Issue 8, 17 April 2003 Page(s):656 - 658
Digital Object Identifier 10.1049/el:20030442
[AbstractPlus](#) | Full Text: [PDF\(344 KB\)](#) IEEE JNL
- ☐ 4. **Anodic bonding of optical fibers to silicon for integrating MEMS based op**
and temperature sensors onto optical fibers
Saran, A.; Abeysinghe, D.C.; Deshmukh, P.; Flenniken, R.; Boyd, J.T.;
TRANSDUCERS, Solid-State Sensors, Actuators and Microsystems, 12th Inter
Conference on, 2003
Volume 1, 8-12 June 2003 Page(s):564 - 567 vol.1
[AbstractPlus](#) | Full Text: [PDF\(363 KB\)](#) IEEE CNF
- ☐ 5. **Predicting hysteretic oscillations in over-temperature protection of a pow**
transient electrothermal circuit simulation
Williams, R.K.; Sevilla, L.T.; Rodamaker, M.C.;
Power Semiconductor Devices and ICs, 1993. ISPSD '93. Proceedings of the
Symposium on
18-20 May 1993 Page(s):304 - 309
Digital Object Identifier 10.1109/ISPSD.1993.297143

[AbstractPlus](#) | Full Text: [PDF\(412 KB\)](#) IEEE CNF

- ☐ **6. Design and fabrication of a novel crystal SiGeC far infrared sensor with w micrometer**
Ming-Chun Hsieh; Yean-Kuen Fang; Pei-Ming Wu; Chun-Che Yang; Yu-Cheng Wang; Shyh-Fann Ting; Jyh-Jier Ho;
Sensors Journal, IEEE
Volume 2, Issue 4, Aug. 2002 Page(s):360 - 365
Digital Object Identifier 10.1109/JSEN.2002.802249
[AbstractPlus](#) | [References](#) | Full Text: [PDF\(639 KB\)](#) IEEE JNL

- ☐ **7. Characterization of surface acoustic wave propagation in a ZnO layer on substrate**
Smole, P.; Ruile, W.; Pongratz, P.;
Ultrasonics Symposium, 2002. Proceedings. 2002 IEEE
Volume 1, 8-11 Oct. 2002 Page(s):307 - 310 vol.1
[AbstractPlus](#) | Full Text: [PDF\(398 KB\)](#) IEEE CNF

- ☐ **8. Simulation and design of the silicon drag-force-gas flowsensor based on effect**
Kolchuzhin, V.A.; Shaporin, A.V.;
Sensors, 2002. Proceedings of IEEE
Volume 1, 12-14 June 2002 Page(s):627 - 632 vol.1
Digital Object Identifier 10.1109/ICSENS.2002.1037174
[AbstractPlus](#) | Full Text: [PDF\(398 KB\)](#) IEEE CNF

- ☐ **9. Solder joint shape and standoff height prediction and integration with FE methodology for reliability evaluation**
Sidharth; Blish, R.; Natekar, D.;
Electronic Components and Technology Conference, 2002. Proceedings. 52nc
28-31 May 2002 Page(s):1739 - 1744
Digital Object Identifier 10.1109/ECTC.2002.1008345
[AbstractPlus](#) | Full Text: [PDF\(726 KB\)](#) IEEE CNF

- ☐ **10. A silicon piezoresistive pressure sensor**
Singh, R.; Low Lee Ngo; Ho Soon Seng; Mok, F.N.C.;
Electronic Design, Test and Applications, 2002. Proceedings. The First IEEE I Workshop on
29-31 Jan. 2002 Page(s):181 - 184
Digital Object Identifier 10.1109/DELTA.2002.994611
[AbstractPlus](#) | Full Text: [PDF\(356 KB\)](#) IEEE CNF

- ☐ **11. Heat analysis on insulated metal substrates [power electronics]**
Yonemura, N.; Fukuda, M.; Shigi, T.;
Industry Applications Conference, 1996. Thirty-First IAS Annual Meeting, IAS ' Record of the 1996 IEEE
Volume 3, 6-10 Oct. 1996 Page(s):1407 - 1410 vol.3
Digital Object Identifier 10.1109/IAS.1996.559249
[AbstractPlus](#) | Full Text: [PDF\(280 KB\)](#) IEEE CNF

- ☐ **12. Numerical optimization of a heat sink used for electric motor drives**
Gordon, M.H.; Stewart, M.B.; King, B.; Balda, J.C.; Olejniczak, K.J.;
Industry Applications Conference, 1995. Thirtieth IAS Annual Meeting, IAS '95 Record of the 1995 IEEE
Volume 2, 8-12 Oct. 1995 Page(s):967 - 970 vol.2
Digital Object Identifier 10.1109/IAS.1995.530405
[AbstractPlus](#) | Full Text: [PDF\(456 KB\)](#) IEEE CNF

13. Double-Sided IPEM Cooling Using Miniature Heat Pipes

Martens T. J. ; Nellis G. F. ; Pfothenhauer J. M. ; Jahns T. M. ;

IEEE Transactions on Components and Packaging Technologies : Accepted for publication

Volume PP, Issue 99, 2005 Page(s):1 - 10

Digital Object Identifier 10.1109/TCAPT.2005.848591

[AbstractPlus](#) | Full Text: [PDF](#)(1704 KB) IEEE JNLIndexed by
 Inspec[Help](#) [Contact Us](#) [Privacy & :](#)

© Copyright 2005 IEEE -